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AMENDMENTS TO THE CLAIMS

1. (Original) A compound comprising:

at least one epoxy group;

a melting point temperature that is less than 140°C; and

liquid crystallinity at a temperature greater than 150°C.
2. (Original) A composition comprising:

the compound of claim 1; and

a filler having a coefficient of thermal expansion that is comparable to that of silicon.
3. (Withdrawn) A method comprising:

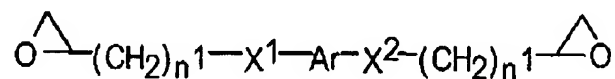
contacting a surface of a microelectronic device with the composition of claim 2;

and

solidifying the composition on the surface.
4. (Withdrawn) A microelectronic device comprising:

a surface; and

a composition solidified on the surface by the method of claim 3.
5. (Original) The compound of claim 1, having the formula:



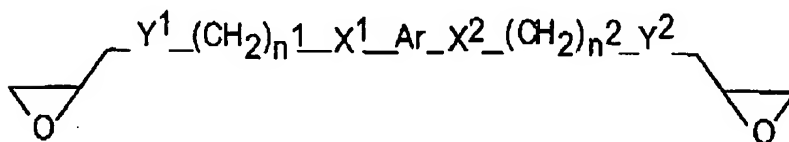
wherein

Ar includes a liquid crystalline moiety selected from trans-stilbenediyl, triphenyl, 1,4-bis(phenoxy carbonyl)cyclohexdiyl, and diphenyl 1,4-cyclohexane-dicarboxylate;

X¹ and X² independently of one another are selected from oxygen, carbonyl, carboxyl, oxycarbonyl, and amine; and

n¹ and n² independently of one another are numbers selected from 4 to 6.

6. (Original) The compound of claim 1, having the formula:



wherein

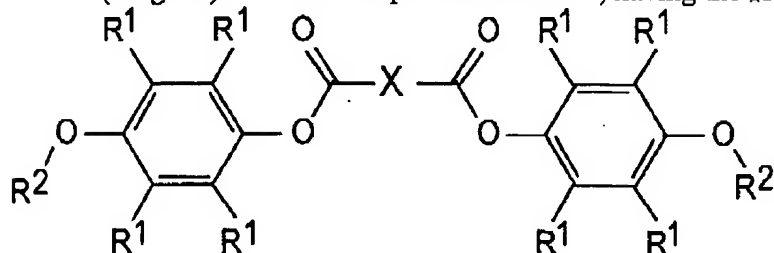
Ar includes a liquid crystalline moiety selected from trans-stilbenediyl, triphenyl, 1,4-bis(phenoxy carbonyl)cyclohexdiyl, diphenyl 1,4-cyclohexanedicarboxylate;

X¹ and X² independently of one another are selected from oxygen, carbonyl, carboxyl, oxycarbonyl, and amine;

Y¹ and Y² independently of one another are selected from oxygen, carbonyl, carboxyl, oxycarbonyl, and amine; and

n¹ and n² independently of one another are numbers selected from 4 to 6.

7. (Original) The compound of claim 1, having the formula:



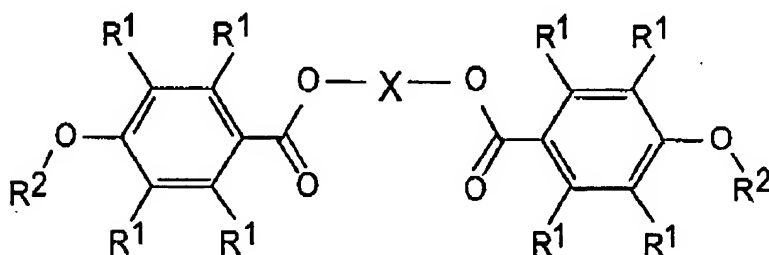
wherein

X is selected from a C₆₋₁₀ aryl group and a C₅₋₁₀ alicyclic group;

each R¹ is independently selected from hydrogen, halogen, and C₁₋₃ alkyl optionally substituted with halogen, provided that not more than four of the R¹ are C₂ alkyl optionally substituted with halogen, and provided that not more than three of the R¹ are C₃ alkyl optionally substituted with halogen; and

each R² is independently selected from a C₂₋₆ epoxy.

8. (Original) The compound of claim 1, having the formula:



wherein

X is selected from a C₆₋₁₀ aryl group and a C₅₋₁₀ alicyclic group;

each R¹ is independently selected from hydrogen, halogen, and C₁₋₃ alkyl optionally substituted with halogen, provided that not more than four of the R¹ are

C₂ alkyl optionally substituted with halogen, and provided that not more than three of the R¹ are C₃ alkyl optionally substituted with halogen;
each R² is independently selected from a C₂₋₆ epoxy.

9. – 48. (Cancelled)

49. (New) The composition of claim 2, wherein the coefficient of thermal expansion of the filler is matched to that of silicon.
50. (New) The composition of claim 2, wherein the filler comprises one or more selected from silicon particles, silica particles, sand, quartz, silicon dioxide, and clay.
51. (New) The composition of claim 2, wherein a weight percent of the filler in the composition ranges from 50 to 95 wt%.
52. (New) The composition of claim 2, wherein the composition comprises an epoxy molding composition.
53. (New) The composition of claim 2, further comprising:

a curing agent;

a curing accelerator; and

a curing inhibitor.